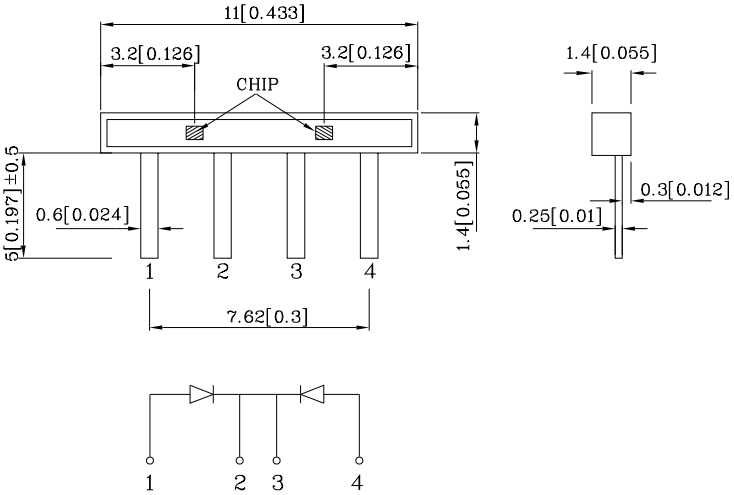
SunLED
www.SunLEDusa.com

Part Number: XZDG66S

11mm x 1.4mm SIDE VIEW

Features

- Low power consumption.
- Ideal for backlighting.
- RoHS compliant.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T_A=25°C)		**DG (InGaN)**	**Unit**
Reverse Voltage	V_R	5	V
Forward Current	I_F	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	150	mA
Power Dissipation	P_D	102.5	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]		260°C For 3 Seconds	
Lead Solder Temperature [5mm Below Package Base]		260°C For 5 Seconds	

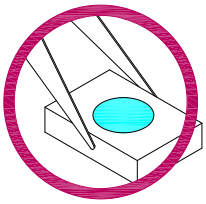
Operating Characteristics (T_A=25°C)		**DG (InGaN)**	**Unit**
Forward Voltage (Typ.) (I_F=20mA)	V_F	3.3	V
Forward Voltage (Max.) (I_F=20mA)	V_F	4.1	V
Reverse Current (Max.) (V_R=5V)	I_R	50	uA
Wavelength of Peak Emission (Typ.) (I_F=20mA)	λ P	515	nm
Wavelength of Dominant Emission (Typ.) (I_F=20mA)	λ D	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I_F=20mA)	Δλ	30	nm
Capacitance (Typ.) (V_F=0V, f=1MHz)	C	45	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZDG66S	Green	InGaN	Water Clear	200	427	515	120°

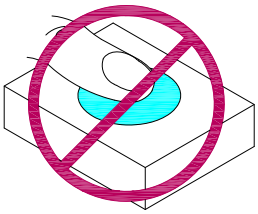
Handling Precautions

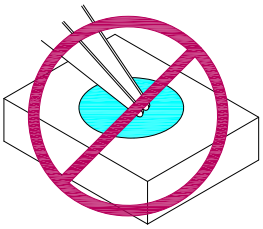
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

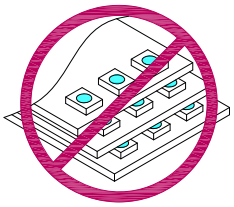


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

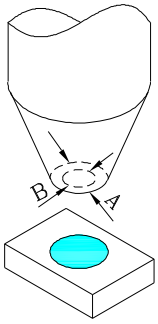


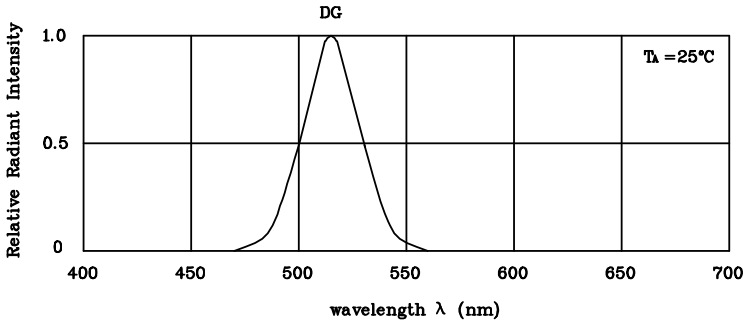


3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



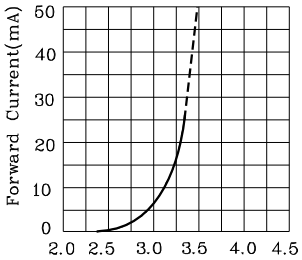
4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



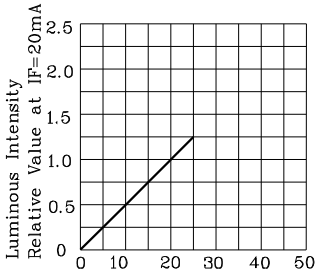


RELATIVE INTENSITY Vs. WAVELENGTH

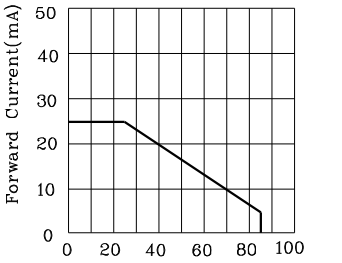
❖ DG



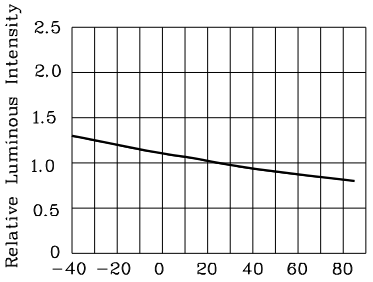
FORWARD CURRENT Vs.
FORWARD VOLTAGE



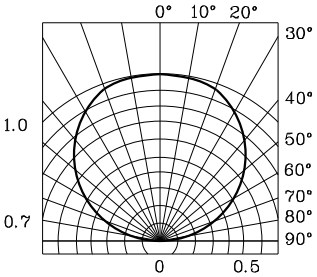
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE

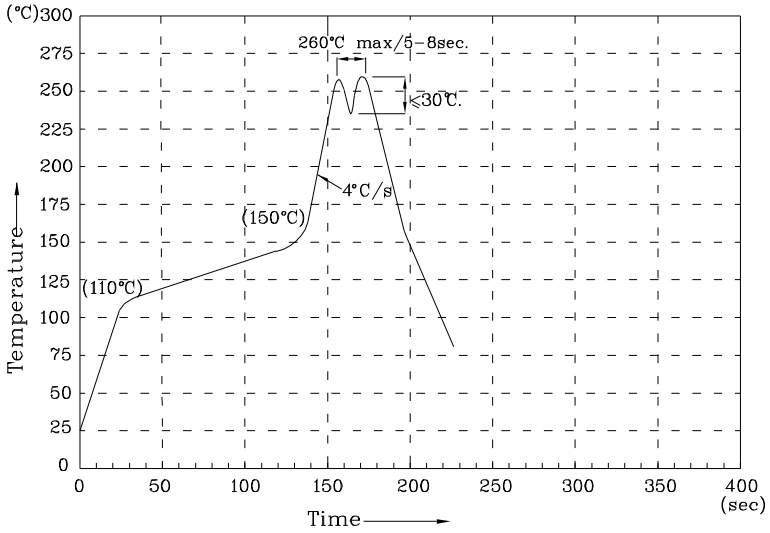


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

Wave Soldering Profile For Lead-free Through-hole LED.



NOTE:

1. Recommend the wave temperature 245℃~260℃.The maximum soldering temperature should be less than 260℃.
2. Do not apply stress on epoxy resins when temperature is over 85 degree℃.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS XZDG66S